



APT

ABLEPRINT

Void Free & Cost Saving Solution Provider

APT Introduction

Solution

Best machine

Oct. 2015

Good material

APT **ABLEPRINT**
Void Free Solution Provider

Confidential

APT History

The APT logo is displayed in red, bold, italicized capital letters.

Establishment: 2007

The APT logo is displayed in red, bold, italicized capital letters.

Location: Zhunan, Taiwan

The APT logo is displayed in red, bold, italicized capital letters.

Capital: 30M NTD

The APT logo is displayed in red, bold, italicized capital letters.

Employee: 30

The APT logo is displayed in red, bold, italicized capital letters.

Position: Being a process-oriented equipment company with dedicated mission of offering competitive alternatives to make any possibilities happen for process improvement, cost-down and driving into production shortly.

APT History

APT

Achievements: APT helps customers to solve process issue through leveraging the necessary need of machine and material each to submit what customer wants instead of pursuing expensive solution. Up-to-date, over 600 system have been delivered.

APT

History:

- 2007, the first VFS applied for SEMI. industry
- 2009, the first VFS applied for O.E. industry
- 2011, the first VFS applied for Flip Chip NUF
- 2012, VFS 250th set shipped.
- 2013, Automation team was established
- 2014, the first VTS applied for Flip Chip CUF
- 2015, the first Automation VTS (VTAS) applied for SEMI. Industry
- 2015, the first MIJ applied for legend and coating for SEMI. Industry.

Confidential

APT Core Competency

Industry

- Semiconductors
- Optoelectronics
- PCB
- MEMS
- Automobile
- EMS

Materials

- Cost effective
- Unique material

Process

Process

- Lamination
- Die Bonding
- FC Bonding
- TCB Bonding
- CUF Dispensing
- Encapsulating
- Reflow
- Via filling

Features

- Customization
- Dedicated Support
- New Application
- Unique Know-how

Material

**Robust
Design**

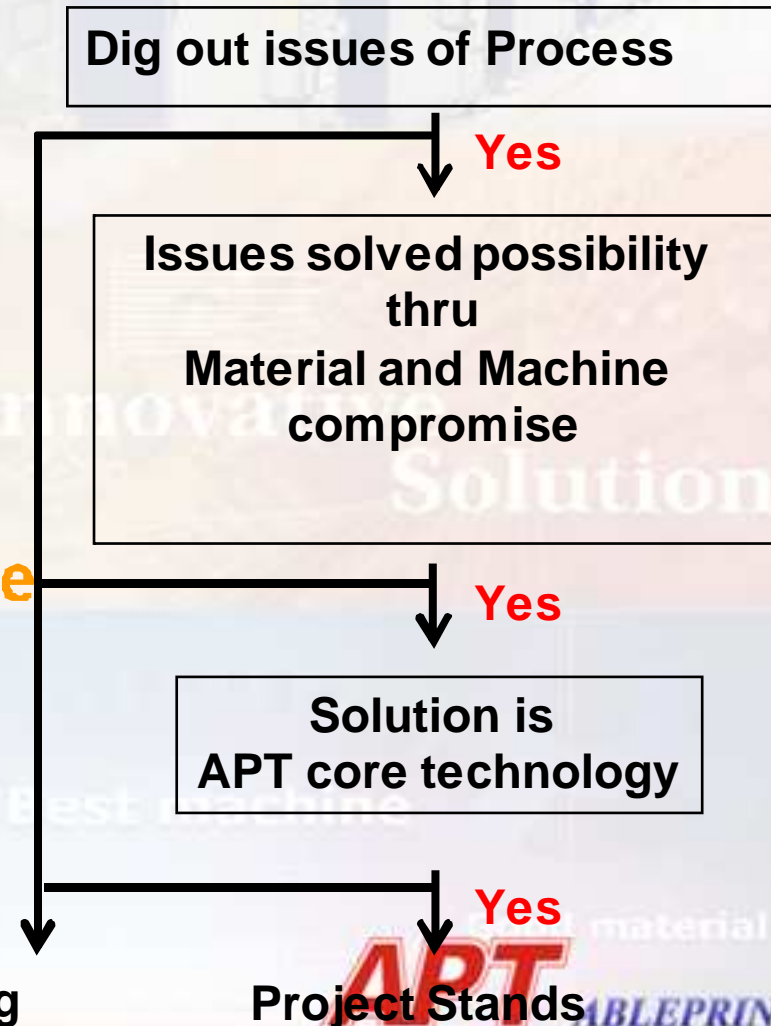
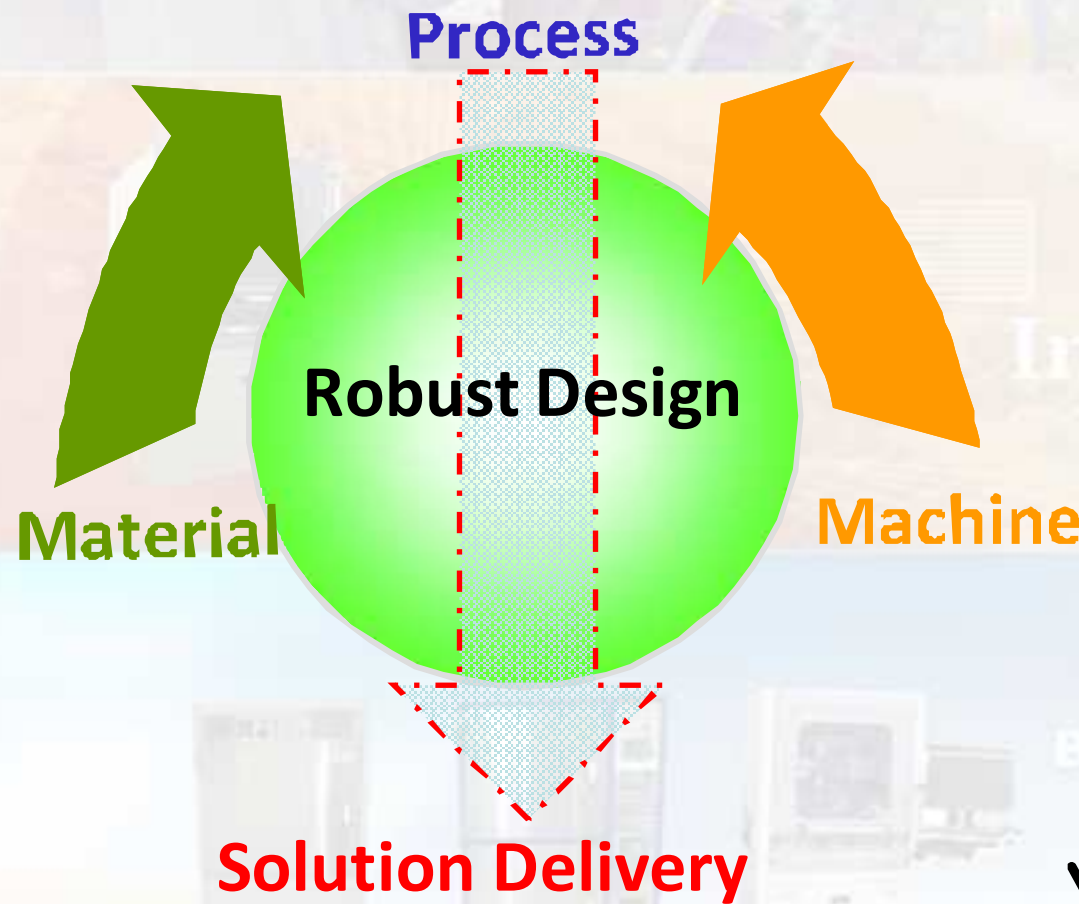
Machine

**Solution
Delivery**

The Way We Choose

We create value, not me too.

Product Evaluation Procedure



APT Product and Applications

Material

NCP/ NCF	DAF/DAP
Flip Chip CUF	Solder/Cu Paste
Sintering Paste	TIM Preform
Polyimide	

Package

2.5D/3D	POP
FCCSP	WLP
MEMS	Embedded
IGBT	LED

Process

waferLamination	CUF Dispensing
Die Attachment	TCB Bonding
Reflow Soldering	VIA filling
Ink Jet Printing	Encapsulation

Own Products

VFS

Void Free System

VTs

Void Terminator System

PRO

Pressure Reflow Oven

Pioneer+

Polyimide Curing Oven

VTAS

Void Terminator Auto.

WSO

Warpage Suppression Oven

MIJ

Map Inkjet Printer

BUP

Dispenser

w/ Functions

VFS based

Confidential

Application Module

Confidential

VFS⁺

Confidential

APT ABLEPRINT
Void Free Solution Provider

Confidential

APT Product & Process Roadmap

Solutions:

- Cost-effective NCF for 3DIC
- Cost-effective TCB for 3DIC

Solutions:

- Total Cost Saving for FC w/ CUF
- Warpage Suppression for WLP
- Soldering void free for WLP & IGBT

Solutions:

- Cost Saving for FC w/ CUF

2016

2015

2014

Con

Product Portfolio-Void Free System

- Performance: driving higher quality, lower cost, quick phase in MP through eliminating void efficiently.



**2007
VFS**



**2009
Dual VFS**



**2013
Pioneer+**



**2014
VTS**



**2015
VTAS**



**2015
PRO**

Active Solution

Best machine

Good material

APT ABLEPRINT
Void Free Solution Provider

Confidential

Product Portfolio- Automation

- Performance: driving higher quality, lower cost, quick phase in MP through innovative Automation Eq.

Map Ink Jet
Printer

Ultra UPH
Dispenser

Ultra UPH
MGZ cleaner



Best machine

Good material

APT ABLEPRINT
Void Free Solution Provider

Confidential

APT Achieves



Taiwan

Korea

S.E Asia

China

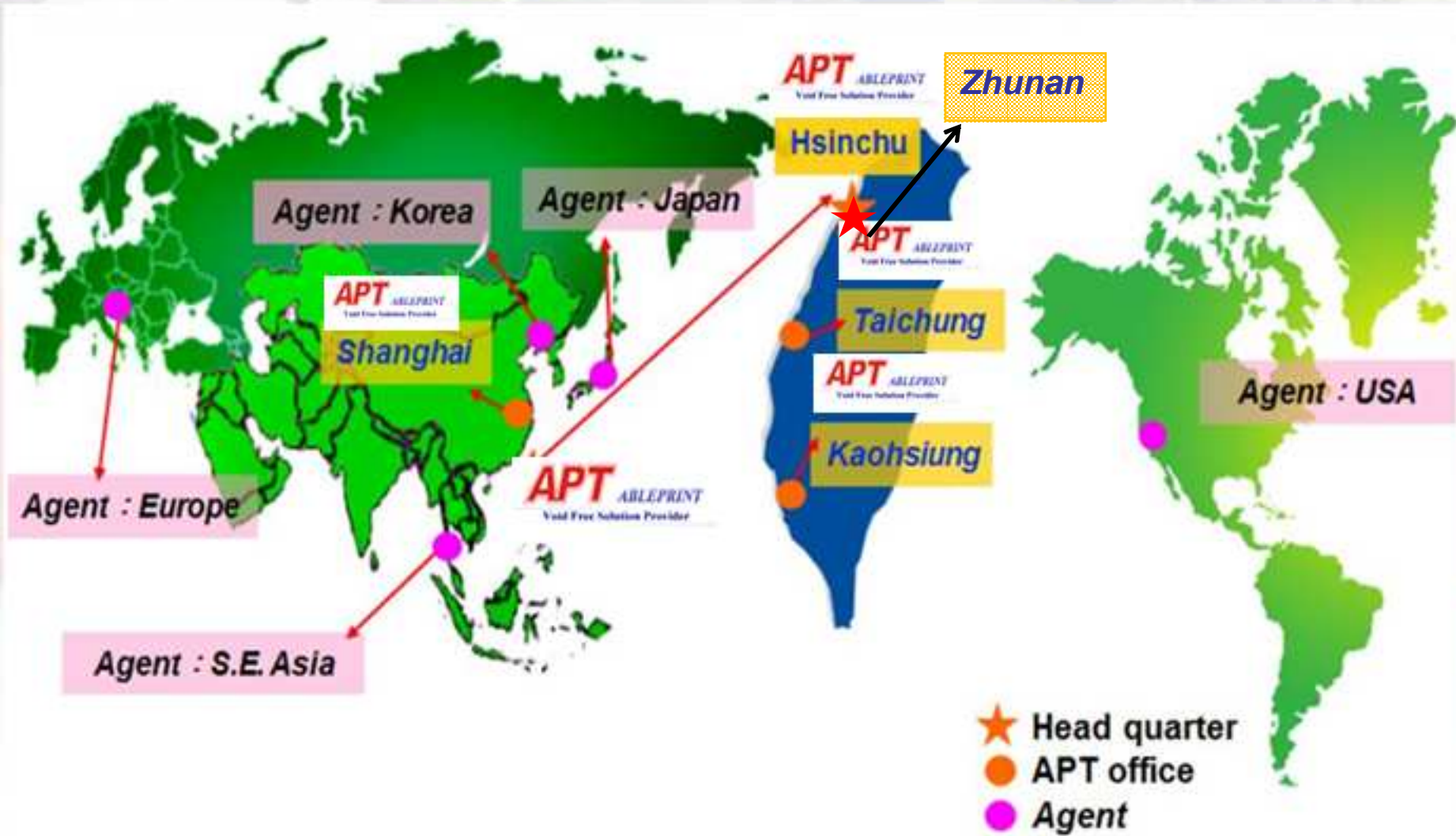
North
America

Japan

Europe

IP
IDM
OSATs
Foundries
Research Lab
Material Supplier

APT Worldwide Support





~Thank you for your attention~

AblePrint Technology Co., Ltd

www.ableprint.com.tw

apt@ableprint.com.tw

Confidential

Best machine

Good material

APT **ABLEPRINT**
Void Free Solution Provider